

2023 IEEE CEIDP

Call for Participation

Best Student Paper Award Competition

The Conference on Electrical Insulation and Dielectric Phenomena Executive Committee and the IEEE DEIS Young Professionals are pleased to announce this call for participation in the first annual Best Student Paper Award Competition during the 2023 IEEE CEIDP in East Rutherford, New Jersey. This competition is anticipated to become a regular feature of CEIDP. Details about the awards, participation and the eligibility are as follows.

Award

- Two student paper awards of \$500 USD each are to be presented in recognition of remarkable contributions in CEIDP fields of interest

Eligibility

- The student must be the primary author of the subject paper.
- The student must present in person at CEIDP, either in an oral or in a poster session.
- The student must be a registered member of IEEE.

Criteria

- Significance and Scientific Content: Findings have a potential impact at the applied or fundamental level (50%).
- Originality: Paper includes novel, unpublished work (40%).
- Clarity and Formatting: Paper is composed of clear and technically sound language with a format that adheres to IEEE guidelines as specified in the conference website (10%).

Participation

- The paper must be submitted via Conftool by the **official** deadline of the full paper submission, i.e., **June 1st, 2023**.
- The student must indicate interest in participating in the competition via Conftool when submitting the full paper.

Selection and Announcement of the Awards

- An award committee from the Technical Program Committee and IEEE DEIS YP will be formed by the TPC Chair to review the participating papers and select the two winners
- The two awarded papers will be selected from papers nominated by the award committee for “The Best Student Paper Award” special session in the CEIDP.
- The winners will be announced by the Conference Chair at the CEIDP gala dinner.